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August 2024

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In Loving Memory: Arvind Mithal

It is with deep sadness that the Council on Electronic Design Automation announces the passing of Arvind Mithal. His impactful contributions to the EDA community will be fondly remembered by all who knew him.

Read More About Arvind

CEDA®
IEEE Council on Electronic Design Automation

2024–2025 DISTINGUISHED LECTURER CLASS

2024-2025 Distinguished Lecturer Class

The IEEE CEDA Distinguished Lecturer Program promotes the field of electronic design automation to the scientific community and the public at large. The goal of the program is to increase awareness about topics relevant to CEDA by creating a pool of subject matter experts and scholars to present to IEEE and CEDA Chapters, Sections and other venues such as universities and companies.

Meet the Class of 2024-2025!

- **Albert Bosio**

- **Sudeep Pasricha**

- **Ricardo Reis**

- **Bei Yu**

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IEEE Internet of Things

Set up in 2023 as an IEEE-wide initiative led by the Communications Society, the Internet of Things Technical Committee (IoT-TC) fosters the exchange of research, development, deployment, education, regulatory, and business aspects in the quickly evolving field of the Internet of Things (IoT).

The Council on EDA has been a main proponent and Core member of this initiative since it started and has recently reaffirmed its commitment to the IoT-TC goals by signing an amendment that enables the Technical Committee to establish means to become self-sufficient in the future, as part of the new IEEE TAB-initiated TC 2.0 process.

Read More

IEEE Embedded Systems Letters (ESL)

We are excited to share a significant update from **IEEE Embedded Systems Letters (ESL)**. In our continued effort to serve the embedded systems research community better, IEEE ESL now guarantees a 1-month turnaround time from submission to the first decision.

This accelerated review process, combined with our concise 4-page paper format, represents a major step towards our mission of being the premier venue for publishing early research results in an easily digestible format. Our goal is to provide researchers with timely feedback and rapid dissemination of their groundbreaking work, ensuring that the latest innovations reach the community without delay.

We invite you to submit your most promising early research findings to IEEE ESL and experience our streamlined publication process.

Learn More

ESWEEK 2024

29 September - 4 October
Raleigh, NC, USA

ESWEEK

Embedded Systems Week (ESWEEK) is the premier event covering all aspects of hardware and software design for intelligent and connected computing systems. By bringing together three leading conferences (CASES, CODES+ISSS, EMSOFT), one symposium (MEMOCODE), and several workshops and tutorials, ESWEEK allows attendees to benefit from a wide range of topics covering the state of the art in embedded systems research and development.

Call for Participation:

- CASES
- CODES+ISSS
- EMSOFT
- MEMOCODE
- Keynotes
- Workshops (LLM-PIM, MSC, RSP, TACPS, TCRS)
- Tutorials
- Education Classes
- Competitions
- Panels

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IEEE Transactions on Circuits and Systems for Artificial Intelligence (TCASAI) Author Portal is Open for Submissions

As the first IEEE periodical dedicated to artificial intelligence (AI) hardware, the **IEEE Transactions on Circuits and Systems for Artificial Intelligence (TCASAI)** publishes contributions related to circuits and systems for artificial intelligence, including circuit and electronic system design, implementation, and demonstration. The IEEE TCASAI is co-sponsored by CEDA.

Officially launched in March 2024, the IEEE TCASAI invites original, high-quality research papers on innovations in hardware designed to execute diverse AI models. These include but are not limited to, digital circuits, analog circuits, mixed-signal circuits, emerging nanodevice-based circuits, FPGA, GPU, CPU, domain-specific circuits, and integrated computing systems. Submissions may also address corresponding optimizations of AI models that consider the constraints and supports of these hardware innovations.

Potential authors can submit their manuscripts through the IEEE Author Portal at: **https://ieee.atyponrex.com/journal/tcasai**

Learn More

Conferences

Embedded Systems Week (ESWEEK 2024)
- 🗓 29 September-4 October 2024
- 📍 Raleigh, NC, USA

2024 ACM/IEEE International Conference on Computer-Aided Design (ICCAD 2024)
- 🗓 27-31 October 2024
- 📍 Newark, New Jersey, USA

Asia and South Pacific Design Automation Conference (ASP-DAC 2025)
- 🗓 20-23 January 2025
- 📍 Tokyo, Japan

Design, Automation, and Test in Europe Conference (DATE 2025)
- 🗓 31 March-2 April 2025
- 📍 Lyon, France

Design Automation Conference (DAC 2025)
- 🗓 22-26 June 2025
- 📍 San Francisco, CA, USA

Contact IEEE CEDA VP of Conferences Tsung-Yi Ho for sponsorship opportunities at **vp.conferences@ieee-ceda.org**.

Publications

IEEE CEDA financially sponsors and co-sponsors several publications and publishes its *Currents* newsletter to inform the EDA community on industry news and research results.

Visit the individual publication pages for more information on publication scope, call for papers, and more.

## Top Accessed Articles in July 2024 (*as of 8 August 2024)

IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems

- **ViA: A Novel Vision-Transformer Accelerator Based on FPGA**
- **TrueNorth: Design and Tool Flow of a 65 mW 1 Million Neuron Programmable Neurosynaptic Chip**
- **NeuroSim: A Circuit-Level Macro Model for Benchmarking Neuro-Inspired Architectures in Online Learning**

IEEE Design&Test

- **High-Bandwidth Memory (HBM) Test Challenges and Solution**
- **Furthering Moore's Law Integration Benefits in the Chiplet Era**
- **Testability and Dependability of AI Hardware: Survey, Trends, Challenges, and Perspectives**
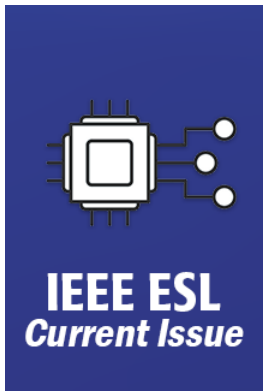
IEEE Embedded Systems Letters

- **An AI-Based Ventilation KPI Using Embedded IoT Devices**
- **On-Device Personalization for Human Activity Recognition on STM32**
- **Embedded Systems Education: Experiences With Application-Driven Pedagogy**

Contact IEEE CEDA VP of Publications Jörg Henkel at **henkel@kit.edu** or the journal's respective EiC for questions regarding CEDA-sponsored publications.

Share what's new

We thank you for forwarding this content to others who might be interested including other members of your group or organization.